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### DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMSD2836 and CMSD2838 are ultra-high speed silicon switching diodes manufactured by the epitaxial planar process, in an epoxy molded SUPERmini<sup>™</sup> surface mount package, designed for high speed switching applications.

The following configurations are available:

CMSD2836 CMSD2838	DUAL, COMMOM ANODE DUAL, COMMON CATHODE	MARKING C MARKING C		
MAXIMUM RATINGS: (T <sub>A</sub> =25°C)		SYMBOL		UNITS
Peak Repetitiv	e Reverse Voltage	VRRM	75	V
Average Forward Current		Ι <sub>Ο</sub>	200	mA
Peak Forward	Current, tp=1.0s	<sup>I</sup> FM	300	mA
Power Dissipa	tion	PD	275	mW
Operating and	Storage Junction Temperature	TJ, T <sub>stg</sub>	-65 to +150	°C
Thermal Resis	tance	$\Theta_{JA}$	455	°C/W

#### ELECTRICAL CHARACTERISTICS PER DIODE: (TA=25°C unless otherwise noted)

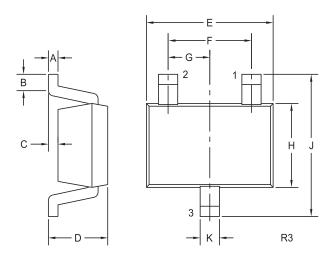
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
IR	V <sub>R</sub> =50V			100	nA
BVR	I <sub>R</sub> =100μΑ	75			V
VF	I <sub>F</sub> =10mA			1.0	V
VF	I <sub>F</sub> =50mA			1.0	V
VF	I <sub>F</sub> =100mA			1.2	V
CT	V <sub>R</sub> =0, f=1.0MHz		1.5	4.0	pF
t <sub>rr</sub>	$I_R=I_F=10$ mA, $I_{rr}=1.0$ mA, $R_L=100\Omega$			4.0	ns

R4 (8-February 2010)



#### CMSD2836 CMSD2838

#### SURFACE MOUNT DUAL SILICON SWITCHING DIODES

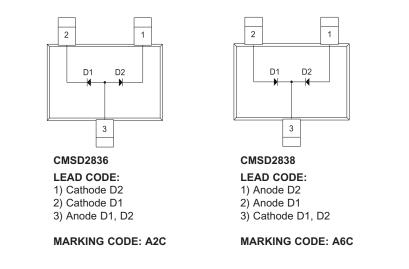


DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
А	0.002	800.0	0.05	0.20			
В	0.004	-	0.10	-			
С	-	0.004	-	0.10			
D	0.031	0.043	0.80	1.10			
E	0.071	0.087	1.80	2.20			
F	0.051		1.30				
G	0.026		0.65				
Н	0.045	0.053	1.15	1.35			
J	0.079	0.087	2.00	2.20			
K	0.008	0.016	0.20	0.40			
SUL 333 (DE//- D3)							

SOT-323 (REV: R3)

#### PIN CONFIGURATIONS

SOT-323 CASE - MECHANICAL OUTLINE



R4 (8-February 2010)

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# OUTSTANDING SUPPORT AND SUPERIOR SERVICES



### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

## DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

Special wafer diffusions

· Custom product packing

- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

· Custom bar coding for shipments

Custom product and package development

### REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

### CONTACT US

#### Corporate Headquarters & Customer Support Team

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